*Customer:

SPECIFICATION

ITEM	TOP LED DEVICE		
MODEL	SSC-WRT801		

[Contents]

1.	Features	2
2.	Application	2
3.	Absolute Maximum Ratings	3
4.	Electro-optical Characteristics	3
5.	Soldering Profile	4
6.	Outline Dimension	5
7.	Packing	5
8.	Reel Packing Structure	6
9.	Precaution for Use	7
10.	Characteristic Diagram	8

Drawn by	Checked by	Approved by

1. Fe	Features	
	White colored SMT package and colorless clear window	
□ Ma	Material : AlGaInP	
□ Sui	Suitable for all SMT assembly methods; Suitable for all soldering methods	
2. Ap	Application	
-	Electric appliance	
□ Lig	Lightings	

3. Absolute Maximum Ratings *1

 $(T_a=25^{\circ}C)$

Parameter	Symbol	Value	Unit
Power Dissipation	P_d	90	mW
Forward Current	I_F	30	mA
Peak Forward Current	I_{FM} *2	100	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +100	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C

^{*1} Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.

4. Electro-Optical Characteristics

 $(T_a=25^{\circ}C)$

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	V_F	$I_F = 20 \text{mA}$	1.8	2.2	2.6	V
Reverse Current	I_R	V_R =5V	-	-	10	μΑ
Luminance Intensity *1	I_V	$I_F = 20 \text{mA}$	260	320	500	mcd
Peak Wavelength	λ_P	I_F =20mA	-	640	-	nm
Dominant Wavelength	λ_d	$I_F = 20 \text{mA}$	619	625	631	nm
Spectral Bandwidth 50%	Δλ	$I_F = 20 \text{mA}$	-	18	-	nm
Viewing Angle *2	2θ _½	$I_F = 20 \text{mA}$	-	120	-	deg.

^{*1} The luminous intensity I_V is measured at the peak of the spatial pattern which may not be aligned with the mechanical axis of the LED package. Luminous Intensity Measurement allowance is $\pm 10\%$.

[Note] All measurements were made under the standardized environment of SSC.

^{*2} I_{FM} was measured at $T_W \leq 0.1$ msec of pulse width and D $\leq 1/10$ of duty ratio.

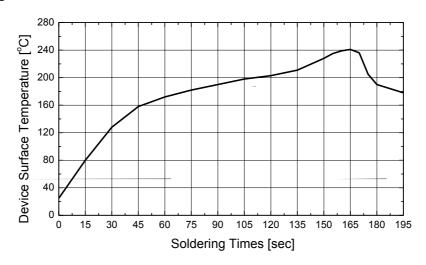
^{*2} $2\theta_{1/2}$ was the off-axis where the luminous intensity is 1/2 of the peak intensity.

5. Soldering Profile

(1) Reflow Soldering Conditions / Profile

Preliminary heat to be at maximum 150°C for maximum 2 minutes.

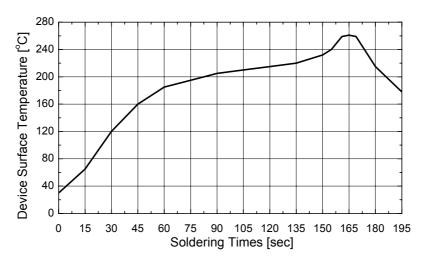
Soldering heat to be at maximum 240°C for maximum 10 seconds.



(2) Lead-free solder

Preliminary heating to be at maximum 220°C for maximum 2 minutes.

Soldering heat to be at maximum 260°C for maximum 10 seconds.

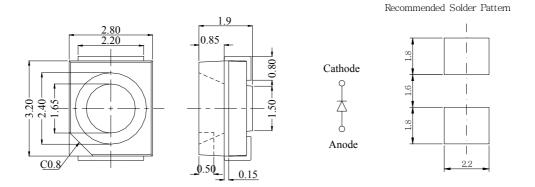


(3) Hand Soldering conditions

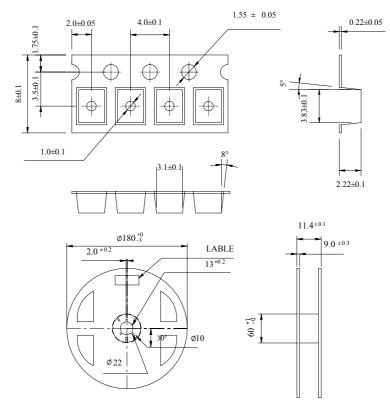
Not more than 5 seconds @MAX300°C, under Soldering iron.

In case the soldered products are reused in soldering process, we don't guarantee the products.

6. Outline Dimension



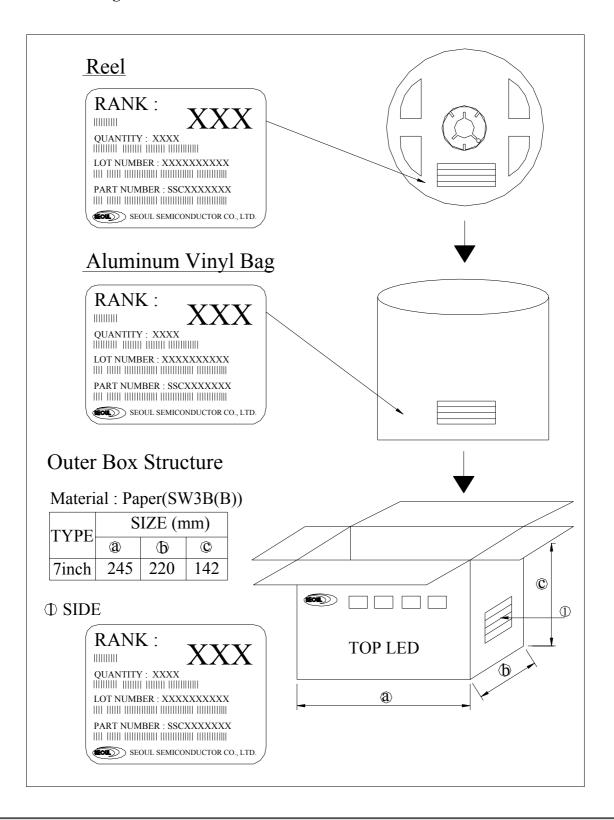
7. Packing



(Tolerance: ± 0.2 , Unit: mm)

- (1) Quantity: 2000pcs/Reel
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be ± 0.2 mm
- (3) Adhesion Strength of Cover Tape: Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10° to the carrier tape
- (4) Package: P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package

8. Reel Packing Structure



9. Precaution for use

(1) Storage

In order to avoid the absorption of moisture, it is recommended to store in a dry box (or a desiccator) with a desiccant. Otherwise, to store them in the following environment is recommended.

Temperature: 5°C ~30°C Humidity: maximum 60%HR

- * The LED is classified to Class 3 by JEDEC (J-STD-020A and J-STD-033).
- (2) Attention after open.

LED is correspond to SMD, when LED be soldered dip, interfacial separation may affect the light transmission efficiency, causing the light intensity to drop. Attention in followed;

- a. After opened and mounted the soldering shall be quickly.
- b. Keeping of a fraction

Temperature : $5 \sim 40^{\circ}$ C Humidity : less than 30%

- (3) In the case of more than 1 week passed after opening or change color of indicator on desiccant, components shall be dried 10-12hr. at $60\pm5^{\circ}$ C.
- (4) In the case of that the components is humided, the components shall be dried;

24Hr at 80 ± 5 °C or 12Hr at 100 ± 5 °C.

- (5) Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- (6) Quick cooling shall be avoided.
- (7) Components shall not be mounted on warped direction of L/F.
- (8) Anti radioactive ray design is not considered for the products.
- (9) This device should not be used in any type of fluid such as water, oil, organic solvent etc. When washing is required, IPA should be used.
- (10) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.
- (11) LEDs must be stored to maintain a clean atmosphere. If the LEDs are stored for 3 months or more after being shipped from SSC, a sealed container with a nitrogen atmosphere should be used for storage.
- (12) The LEDs must be soldered within seven days after opening the moisture-proof packing.
- (13) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.

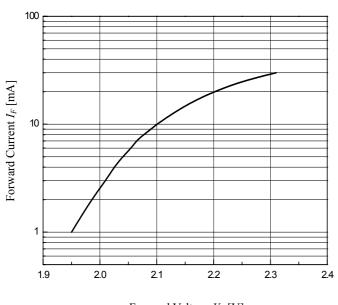
10. Characteristic Diagram

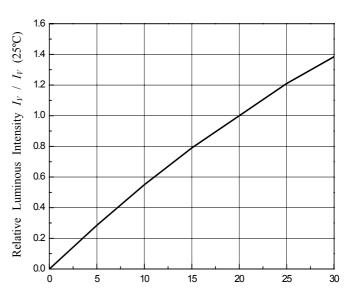
Forward Current vs Forward Voltage

Relative Luminous Intensity vs Forward Current



 $(T_a=25^{\circ}C)$





Forward Voltage $V_F[V]$

Forward Current I_F [mA]

Forward Current Derating Curve

Radiation Diagram

 $(T_a=25^{\circ}\mathrm{C})$

